

**T0-220-3L Plastic-Encapsulate MOSFETS****CJP71N90** N-Channel MOSFET**DESCRIPTION**

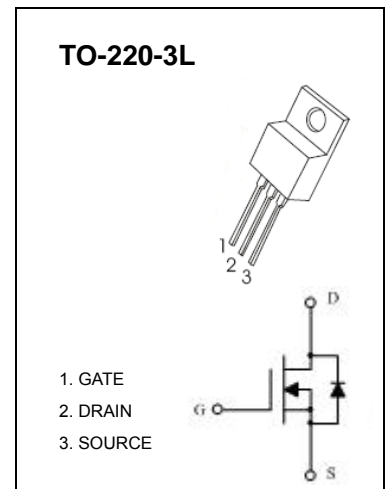
The CJP71N90 uses advanced trench technology and design to provide excellent  $R_{DS(on)}$  with low gate charge. This device is suitable for use in a wide variety of applications.

**FEATURES**

- Lead free product is acquired
- Special process technology for high ESD capability
- High density cell design for ultra low  $R_{DS(on)}$
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation

**APPLICATION**

- Power switching application
- Hard switching and high frequency circuits
- Uninterruptible power supply

**Maximum ratings ( $T_a=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	71	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	90	A
Pulsed Drain Current ( <b>note 1</b> )	$I_{DM}$	320	A
Single Pulsed Avalanche Energy ( <b>note 5</b> )	$E_{AS}$	580	mJ
Thermal Resistance from Junction to Ambient ( <b>note 2</b> )	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~+150	$^\circ\text{C}$

## Electrical characteristics (T<sub>a</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>STATIC CHARACTERISTICS</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	71			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 71V, V <sub>GS</sub> = 0V			1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			± 100	nA
Gate threshold voltage <b>(note 3)</b>	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2		4	V
Drain-source on-resistance <b>(note 3)</b>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 40A			7.5	mΩ
Forward transconductance <b>(note 3)</b>	g <sub>FS</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 40A		60		S
Diode forward voltage <b>(note 3)</b>	V <sub>SD</sub>	I <sub>S</sub> = 20A, V <sub>GS</sub> = 0V			1.2	V
<b>DYNAMIC CHARACTERISTICS (note 4)</b>						
Input capacitance	C <sub>iSS</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1MHz		4871		pF
Output capacitance	C <sub>oSS</sub>			630.6		pF
Reverse transfer capacitance	C <sub>rSS</sub>			410.3		pF
Gate resistance	R <sub>g</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz		0.63		Ω
<b>SWITCHING CHARACTERISTICS (note 4)</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 30V, R <sub>GEN</sub> = 10Ω, I <sub>D</sub> = 42A		36.1		ns
Turn-on rise time	t <sub>r</sub>			54.3		ns
Turn-off delay time	t <sub>d(off)</sub>			85.2		ns
Turn-off fall time	t <sub>f</sub>			37.3		ns
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> = 48V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 84A		85.7		nC
Gate-source Charge	Q <sub>gs</sub>			23.2		nC
Gate-drain Charge	Q <sub>gd</sub>			31.2		nC
Body diode reverse recovery time <b>(note 3)</b>	t <sub>rr</sub>	I <sub>F</sub> = 84A, di/dt = 100A/μs		88.3		ns
Body diode reverse recovery charge <b>(note 3)</b>	Q <sub>rr</sub>			65.9		nC

### Notes :

1. Repetitive rating : Pulse width limited by junction temperature.
2. Surface mounted on FR4 board , t<sub>s</sub> ≤ 10s.
3. Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to producing.
5. L = 0.5mH, V<sub>DD</sub> = 37.5V, V<sub>GS</sub> = 10V, R<sub>G</sub> = 25Ω, Starting T<sub>J</sub> = 25°C .